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GP1A30R

Features

- 1. 2-phase (A, B) digital output
- 2. Possible to use plastic disk
- 3. High sensing accuracy (Disk slit pitch: 0.7mm)
- 4. TTL compatible output
- 5. Compact and light

Applications

- 1. Electronic typewriters, printers
- 2. Numerical control machines

Adsolute Maximum Ratings			(1a = 25 C)		
	Parameter	Symbol	Rating	Unit	
Input	Forward current	IF	65	mA	
	*1Peak forward current	IFM	1	A	
	Reverse voltage	VR	6	V	
	Power dissipation	Р	100	mW	
Output	Supply voltage	V _{CC}	7	V	
	Low level output current	Iol	20	mA	
	Power dissipation	Po	250	mW	
Operating temperature		Topr	0 to + 70	°C	
Storage temperature		T _{stg}	- 40 to + 80	°C	
*2Soldering temperature		T _{sol}	260	°C	

Absolute Maximum Batings r°

OPIC Photointerrupter with Encoder Function



*" OPIC" (Optical IC) is a trademark of the SHARP Corporation. An OPIC consists of a light-detecting element and signalprocessing circuit integrated onto a single chip.

Electro-optical Characteristics

(Unless	otherwise	specified,	Ta = 0 to +	70°C)
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	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	VF	Ta= 25°C, I _F = 30mA	-	1.2	1.5	V
	Reverse current	IR	Ta= 25° C, V _R = 3V	-	-	10	μΑ
Output	Operating supply voltage	Vcc		4.5	5.0	5.5	V
	High level output voltage	V _{OH}	$^{*3}V_{CC}$ = 5V, I _F = 30mA	2.4	4.9	-	V
	Low level output voltage	Vol	$^{*3}I_{OL} = 8mA, V_{CC} = 5V, I_F = 30mA$	-	0.1	0.4	V
	Supply current	Icc	*3*4 I _F = 30mA, V _{CC} = 5V	-	5	20	mA
Transfer charac- teristics	Duty ratio	*5DA	$V_{CC}=5V, I_{F}=30mA,$	20	50	80	%
		*5DB	* ³ f= 2.5kHz	20	50	80	%
	Response frequency	f MAX.	^{*3} V _{CC} = 5V, I _F = 30mA	-	-	5	kHz

*3 Measured under the condition shown in Measurement Conditions.

*4 In the condition that output A and B are low level.

$$^{*5}D_{A} = \frac{t_{AH}}{t_{AP}} \ge 100, \quad D_{B} = \frac{t_{BH}}{t_{BP}} \ge 100$$

In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that occur in equipment using any of SHARP's devices, shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest version of the device specification sheets before using any SHARP's device."

Output Waveforms



from OPIC light detector









Fig. 2 Output Power Dissipation vs. Ambient Temperature



Fig. 4 Phase Difference vs. Frequency



Fig. 5 Duty Ratio vs. Ambient Temperature



Fig. 7 Duty Ratio vs. Distance (X direction)



Fig. 9 Duty Ratio vs. Distance (Y direction)







Fig. 8 Phase Difference vs. Distance (X direction)



Fig.10 Phase Difference vs. Distance (Y direction)



Fig.11 Duty Ratio vs. Distance (Z direction)



Measurement Conditions



Precautions for Use

- (1) This module is designed to be operated at I_{F} = 30mA TYP.
- (2) Fixing torque: MAX. 0.6Nm (6kgf cm)
- (3) In order to stabilize power supply line, connect a by-pass capacitor of more than 0.01µF between Vcc and GND near the device.
- (4) As for other general cautions, refer to the chapter "Precautions for Use".





<Basic Design>

$$\begin{split} &R_0 \ (\text{distance between the disk center and half point of a slit}), \\ &P \ (\text{slit pitch}), S_1 \ \text{and} \ S_2 \ (\text{installing position of photointer-rupter}) \ \text{will be provided by the following equations.} \\ &Slit pitch: \ P \ (\text{slit center}) \end{split}$$

$$R_{O} = \frac{N}{120} \times 13.45 \text{ (mm)} \text{ N: number of slits}$$

$$P_{O} = \frac{2 \times p \times R_{O}}{120} \text{ (mm)}$$

$$N = N$$

 $S_1 = R_0 - 1.765 (mm), S_2 = S_1 + 6.7 (mm)$

Note) When the number of slits is changed, values in parenthesis

are also changed according to the number.



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